









SN74LV11A

SCES345E - DECEMBER 2000 - REVISED MAY 2024

# **SN74LV11A Triple 3-Input Positive-AND Gates**

#### 1 Features

- Operation of 2V to 5.5V V<sub>CC</sub>
- Max t<sub>nd</sub> of 7ns at 5V
- Typical V<sub>OLP</sub> (output ground bounce) <0.8V at V<sub>CC</sub>  $= 3.3V, T_A = 25^{\circ}C$
- Typical V<sub>OHV</sub> (output V<sub>OH</sub> undershoot) >2.3V at  $V_{CC} = 3.3V$ , TA = 25°C
- Support mixed-mode voltage operation on all ports
- I<sub>off</sub> supports partial-power-down mode operation
- Latch-up performance exceeds 100mA per JESD 78, Class II

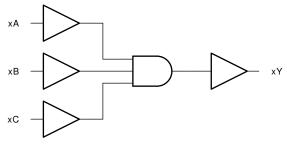
# 2 Description

These triple 3-input positive-AND gates are designed for 2V to 5.5V V<sub>CC</sub> operation.

#### **Package Information**

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE <sup>(1)</sup> PACKAGE SIZE <sup>(2)</sup>		
	DGV (TVSOP, 14)	3.60mm x 6.4mm	3.60mm x 4.4mm	
	D (SOIC, 14)	8.65mm x 6mm	8.65mm x 3. mm	
SN74LV11A	NS (SOP, 14)	10.20mm x 7.8mm	10.3mm x 5.3mm	
	DB (SSOP, 14)	6.20mm x 7.8mm	6.20mm x 5.3mm	
	PW (TSSOP, 14)	5.00mm x 6.4mm	5.00mm x 4.4mm	

- For more information, see Section 10.
- The package size (length × width) is a nominal value and includes pins, where applicable.
- The body size (length × width) is a nominal value and does not include pins.



**Simplified Schematic** 



# **Table of Contents**

1 Features1	6.2 Functional Block Diagram8
2 Description1	6.3 Device Functional Modes8
3 Pin Configuration and Functions3	7 Application and Implementation9
4 Specifications4	7.1 Power Supply Recommendations9
4.1 Absolute Maximum Ratings4	7.2 Layout9
4.2 ESD Ratings4	8 Device and Documentation Support10
4.3 Recommended Operating Conditions4	8.1 Documentation Support (Analog)10
4.4 Thermal Information5	8.2 Receiving Notification of Documentation Updates10
4.5 Switching Characteristics, V <sub>CC</sub> = 2.5 V ± 0.2 V5	8.3 Support Resources10
4.6 Switching Characteristics, V <sub>CC</sub> = 3.3 V ± 0.3 V5	8.4 Trademarks10
4.7 Switching Characteristics, V <sub>CC</sub> = 5 V ± 0.5 V5	8.5 Electrostatic Discharge Caution10
4.8 Noise Characteristics5	8.6 Glossary10
4.9 Operating Characteristics6	9 Revision History10
5 Parameter Measurement Information7	10 Mechanical, Packaging, and Orderable
6 Detailed Description8	Information10
6.1 Overview8	



# 3 Pin Configuration and Functions

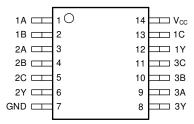


Figure 3-1. SN74LV11A D, NS, DGV, DB, or PW Package (Top View)

P	IN	TYPE(1)	DESCRIPTION				
NAME	NO.	ITPE	DESCRIPTION				
1A	1	I	1A Input				
1B	2	I	1B Input				
2A	3	I	2A Input				
2B	4	1	2B Input				
2C	5	1	2C Input				
2Y	6	0	2Y Output				
3Y	8	0	3Y Output				
ЗА	9	I	3A Input				
3B	10	I	3B Input				
3C	11	I	3C Input				
1Y	12	0	1Y Output				
1C	13	I	1C Input				
GND	7	_	Ground Pin				
V <sub>CC</sub>	14	_	Power Pin				

<sup>(1)</sup> Signal Types: I = Input, O = Output.

# 4 Specifications

## 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	7	V
VI	Input voltage range <sup>(2)</sup>	nput voltage range <sup>(2)</sup>			
Vo	Output voltage range applied in	Output voltage range applied in high or low state <sup>(2) (3)</sup>		V <sub>CC</sub> + 0.5	V
Vo	Output voltage range applied in	n power-off state <sup>(2)</sup>	-0.5	7	V
I <sub>IK</sub>	Input clamp current	(V <sub>I</sub> < 0)		-20	mA
I <sub>OK</sub>	Output clamp current	(V <sub>O</sub> < 0)		-50	mA
Io	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		±25	mA
	Continuous current through V <sub>C</sub>	<sub>C</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 4.2 ESD Ratings

			VALUE	UNIT
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101 (2)	±1000	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

## 4.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
	High lovel input veltage	V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7		V
V <sub>IH</sub>	High level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7		V
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 2 V		0.5	
	Low level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		V <sub>CC</sub> × 0.3	V
V <sub>IL</sub>		V <sub>CC</sub> = 3 V to 3.6 V		V <sub>CC</sub> × 0.3	V
		V <sub>CC</sub> = 4.5 V to 5.5 V		V <sub>CC</sub> × 0.3	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 2 V		-50	μA
	High level autout august	V <sub>CC</sub> = 2.3 V to 2.7 V		-2	
I <sub>OH</sub>	High level output current	V <sub>CC</sub> = 3 V to 3.6 V		-6	mA
		V <sub>CC</sub> = 4.5 V to 5.5 V		-12	

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<sup>2)</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> This value is limited to 5.5 V maximum.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

# 4.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN MAX	UNIT
I <sub>OL</sub>		V <sub>CC</sub> = 2 V	50	μA
	Lour lovel output ourrent	V <sub>CC</sub> = 2.3 V to 2.7 V	2	
	Low level output current	V <sub>CC</sub> = 3 V to 3.6 V	6	mA
		V <sub>CC</sub> = 4.5 V to 5.5 V	12	
		V <sub>CC</sub> = 2.3 V to 2.7 V	200	
Δt/Δν	Input transition rise and fall rate	V <sub>CC</sub> = 3 V to 3.6 V	100	ns/V
		V <sub>CC</sub> = 4.5 V to 5.5 V	20	
T <sub>A</sub>	Operating free-air temperature		-40 85	°C

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004

#### 4.4 Thermal Information

			SN74LV11A					
	THERMAL METRIC <sup>(1)</sup>	D	NS	PW	DB DGV		UNIT	
		14 PINS	14 PINS	14 PINS	14 PINS	14 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	86	76	113	96	127	°C/W	

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report (SPRA953).

# 4.5 Switching Characteristics, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM	то	LOAD	7	Γ <sub>A</sub> = 25°C		SN74LV	11A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 15 pF		6.9	13.8	1	16	no
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 50 pF		9.9	17.5	1	21	ns

# 4.6 Switching Characteristics, V<sub>CC</sub> = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (seeLoad Circuit and Voltage Waveforms)

PARAMETER	FROM	то	LOAD	Т	A = 25°C		SN74LV	′11A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNII
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 15 pF		5.2	8.8	1	10.5	ns
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 50 pF		7.2	12.3	1	14	115

# 4.7 Switching Characteristics, $V_{CC} = 5 V \pm 0.5 V$

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM	то	LOAD	Т	A = 25°C		SN74LV	/11A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNII
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 15 pF		3.9	5.9	1	7	ns
t <sub>pd</sub>	A, B, or C	Y	C <sub>L</sub> = 50 pF		5.4	7.9	1	9	115

#### 4.8 Noise Characteristics

 $V_{CC} = 3.3 \text{ V. } C_1 = 50 \text{ pF. } T_A = 25^{\circ}\text{C}$ 

	PARAMETER <sup>(1)</sup>	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.2	0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		0	-0.8	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		3.2		V

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 $V_{CC}$  = 3.3 V,  $C_L$  = 50 pF,  $T_A$  = 25°C

	PARAMETER <sup>(1)</sup>	MIN	TYP	MAX	UNIT
V <sub>IH(D)</sub>	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

# **4.9 Operating Characteristics**

# T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	TYP	UNIT
Γ	C <sub>nd</sub> Power dissipation capacitance	C <sub>1</sub> = 50 pF, f = 10 MHz	3.3 V	13.9	nE
	C <sub>pd</sub> Fower dissipation capacitance	C <sub>L</sub> = 30 μr, 1 = 10 MHZ	5 V	15.4	p⊦

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#### **5 Parameter Measurement Information**

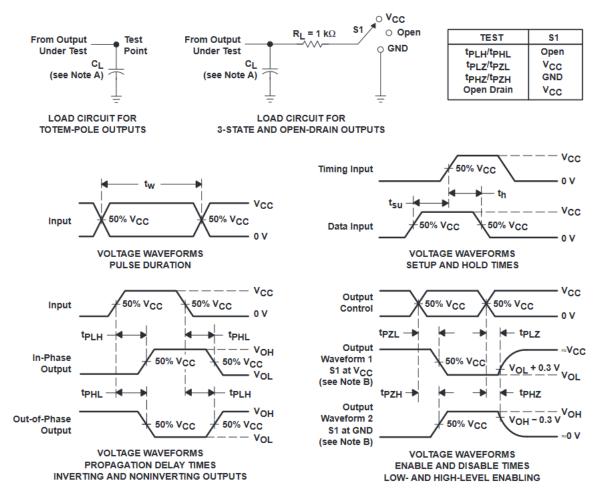


Figure 5-1. Load Circuit and Voltage Waveforms

- A. C<sub>L</sub> includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_r \leq$  3 ns,  $t_f \leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

# **6 Detailed Description**

#### 6.1 Overview

These triple 3-input positive-AND gates are designed for 2-V to 5.5-V V<sub>CC</sub> operation.

The SN74LV11A devices perform the Boolean function  $Y = A \cdot B \cdot C$  or  $Y = \overline{A + B + C}$  in positive logic.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

# 6.2 Functional Block Diagram

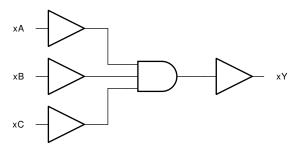


Figure 6-1. Logic Diagram, Each Gate (Positive L9ogic)

#### 6.3 Device Functional Modes

Table 6-1. Function Table (Each Gate)

II	OUTPUT (2)		
Α	В	С	Y
Н	Н	Н	Н
L	Χ	Χ	L
×	L	Χ	L
Х	Χ	L	L

- (1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care
- (2) H = Driving High, L = Driving Low

# 7 Application and Implementation

#### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

## 7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the Recommended Operating Conditions. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

#### 7.2 Layout

#### 7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V<sub>CC</sub>, whichever makes more sense for the logic function or is more convenient.

#### 7.2.2 Layout Example

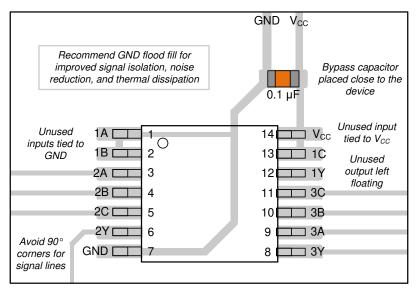


Figure 7-1. Example layout for the SN74LV11A

# 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

#### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PARTS PRODUCT FOLDER		TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY	
SN74LV11A	Click here	Click here	Click here	Click here	Click here	

#### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on Notifications to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

#### 8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

#### 8.4 Trademarks

TI E2E<sup>™</sup> is a trademark of Texas Instruments.

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#### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### 8.6 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

#### 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### Changes from Revision D (April 2015) to Revision E (May 2024)

Page

Added Package Information table, Pin Functions table, ESD Ratings table, Thermal Information table, Device Functional Modes, Application and Implementation section, Device and Documentation Support section, and 

# 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: SN74LV11A

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LV11AD	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	LV11A
SN74LV11ADBR	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ADBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ADGVR	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ADGVR.A	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ADR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11ANSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV11A
SN74LV11ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV11A
SN74LV11APW	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 85	LV11A
SN74LV11APWR	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LV11A
SN74LV11APWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV11A

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE OPTION ADDENDUM**

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN74LV11A:

Automotive : SN74LV11A-Q1

Enhanced Product : SN74LV11A-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION



# TAPE DIMENSIONS KO PI BO Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV11ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV11ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV11ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV11ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV11APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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#### \*All dimensions are nominal

7 till dillitorioriorio di o mominidi							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV11ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LV11ADGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74LV11ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV11ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV11APWR	TSSOP	PW	14	2000	353.0	353.0	32.0



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# DGV (R-PDSO-G\*\*)

## 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194





#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-150.





NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.







#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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